

*A2* 5. (Amended) A resin composition comprising a urethane oligomer (A) according to claim

1 and an unsaturated group-containing polycarboxylic acid resin (B) that is a product obtained by reacting an epoxy resin (e) having at least two epoxy groups per molecule with a monocarboxylic acid compound (f) having ethylenically unsaturated groups and a polybasic acid anhydride (b-2).

*A3* 7. (Amended) A resin composition comprising a urethane oligomer (A) according to claim

1 and a thermoplastic polymer (D).

*A3* 8. (Amended) A resin composition according to claim 5, comprising a diluent (C).

*A3* 9. (Amended) A resin composition according to claim 5, further comprising a diluent (C), and wherein said diluent (C) is a reactive diluent (C-1).

10. (Amended) A resin composition according to claim 5 comprising a photopolymerization initiator (E).

11. (Amended) A resin composition comprising a urethane oligomer (A) according to claim 1, a thermoplastic polymer (D) and a photopolymerization initiator (E).

*A4* 13. (Amended) A resin composition according to claim 5 comprising a thermoplastic component (F).

*A4* 14. (Amended) A resin composition according to claim 5, wherein said resin composition is prepared for the solder resist in a printed circuit board or for an interlayer dielectric layer.

15. (Amended) A photosensitive film comprising being prepared by laminating the layer of a resin composition according to claim 5 on a supporting film.

17. (Amended) A cured product of the resin composition according to claim 5.

*A5* 20. (Cancelled)